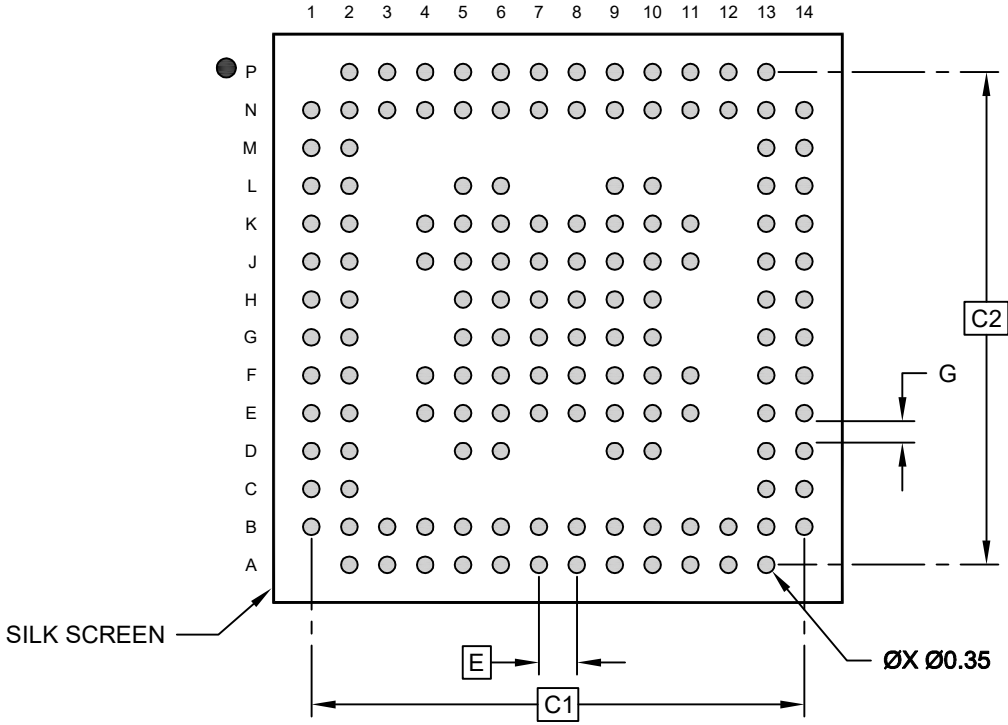


144-Ball Thin Fine-Pitch Ball Grid Array Package (LUX) - 12×12×1.19 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Contact Pad Spacing	C1	10.40 BSC		
Contact Pad Spacing	C2	10.40 BSC		
Contact Pad Width (X144)	X			0.35
Contact Pad to Center Pad	G	0.45		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process